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FIG. 1

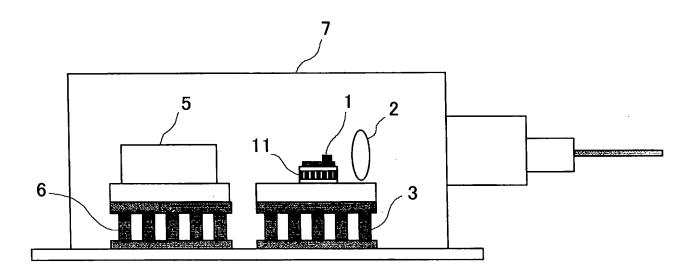
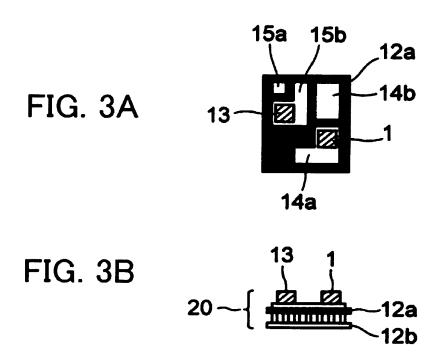


FIG 2

			,	ペルチェ基板面積 $S (mm^2)$	面積S (mm <sup>2</sup>		
		2	4	8	16	32	64
	150	75	37.5	//18.75	9.375	4.6875	2.34375
9	250	125	62.5	31.25	//15.625/	7.8125	3.90625
光数	360	180	06	45	22.5	11.25	//5,625
	009	300%	150	22	37.5	18.75	9.375
y ≥	800	() () ()	200	100	90	25	///12.5/
	1000	500	///250	125	62.5	31.25	//15.625/

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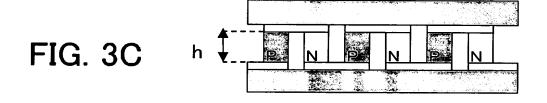


FIG. 4

		\$	7			製	実施例				比較例	<b>2</b> (9)	
			过 <b>由</b>	構造A	構造B	構造 C	健造 D	構造E	構造F	構造G	構造H	構造 [	権高し
P77\	素子発熱量と基板1の面積の比	Qd/S1	mW/mm^2	55.56	55.56	32.61	160.00	55.56	52.08	7.50	20.00	7.03	20.83
770	基板1と基板2の面積比	\$1/\$2		0.090	0.090	0.219	0.031	0.045	0.120	1.000	0.625	1.000	0.750
	TECの形態係数	L	E E	9.07	9.52	24.30	9.22	4.54	12.10	25.79	29.65	36.11	49.41
#RI	基板1の面積	S1	mm^2	6.48	6.48	18.40	2.25	3.24	8.64	48.00	30.00	64.00	48.00
<b>I</b>	チップ底面積の和	Sc1	mm^2	1.81	4.76	8.51	0.92	0.91	2.42	19.60	15.12	27.44	25.20
FK ■	素子発熱量	РЮ	mW	360	360	900	360	180	450	360	909	450	1000
<b>平</b> 木	素子発熱量とチップ底面積の和の比	og/po	mW/mm^2	198.41	75.66	70.55	390.63	198.41	186.01	18.37	39.68	16.40	39.68
※ 劈	消費電力 (環境温度 70°C/LD 温度 0°Cの場合)	М	W	2.50	2.50	4.00	2.10	2.00	3.50	5.00	5.50	5.50	9.00

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FIG. 5

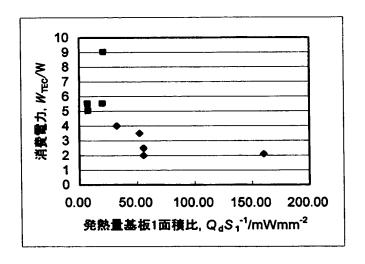


FIG. 6

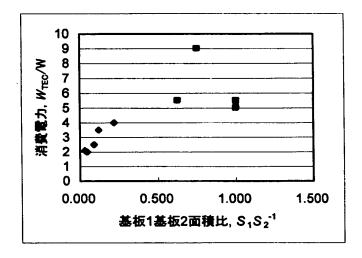


FIG. 7

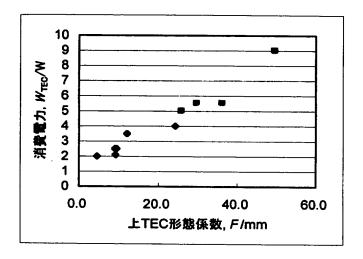
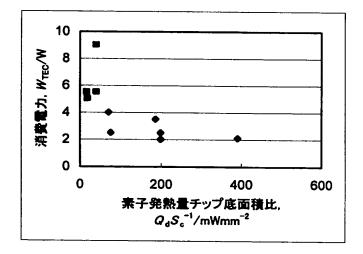


FIG. 8



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FIG. 9

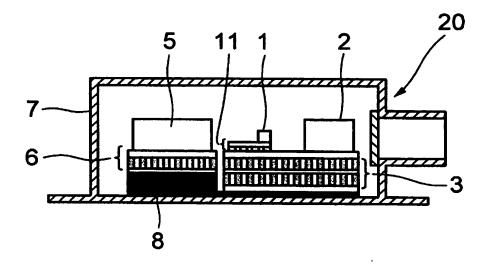


FIG. 10

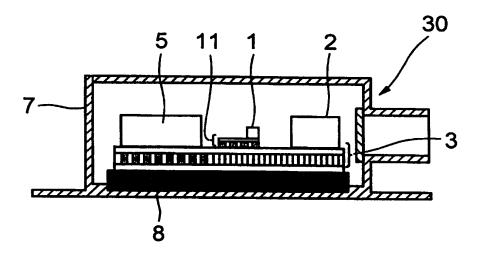


FIG. 11

